



<b>Form Type</b>	Distribute	<b>Version</b>	2.0	<b>Ref</b>	IPC 1752A	<b>Sectionals</b>	Manufacturing Info/ Material Info	<b>Subsectionals</b>	D, A
<b>Supplier Information</b>									
<b>Company Name</b>	TE Connectivity	<b>Request Document ID</b>		<b>Contact Name</b>	Chan, Nelson	<b>Contact Title</b>	Mgr Global Accounts, HKG SELL DIR-EMS		
<b>Company Unique ID</b>	TE Connectivity	<b>Response Date</b>	2016-07-14	<b>Contact Email</b>	nelson.chan@te.com				
<b>Contact Phone Number</b>	+852-2738-8751								
<b>Legal Statement</b>									
<b>Supplier Acceptance</b>	true								
<b>Legal Statement</b>									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
<b>Product</b>									
<b>Manufacturer Item number</b>	2201778-1	<b>Amount</b>	940.3716	<b>Version</b>	-	<b>Identity</b>			
<b>Manufacturer Item Name</b>	MICRO SD PUSH PUSH LOW PROFILE TYPE	<b>Weight Uom</b>	mg	<b>Mfr Site</b>		<b>Authority</b>			
<b>Date</b>		<b>UOM</b>	Each						
<b>EUROHS-0508</b>	Product(s) meets EU RoHS requirement without any exemptions								
<b>ChinaRoHS-0508</b>	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
<b>EUREACH-1215</b>	REACH Candidate Substances of Very High Concern ARE NOT Yet Reviewed								
<b>Manufacturing Information</b>									
<b>J-STD-020 MSL Rating</b>		<b>Max Total a Wave Time</b>		<b>Ramp Rate</b>		<b>Wave Additional Info</b>			
<b>Classification Temp</b>		<b>Max Wave Solder Time</b>	20.0	<b>Ramp Down Rate</b>		<b>Psi Rating Reflow</b>			
<b>Max Time Within 5</b>		<b>Psi Rating Wave</b>		<b>Package Designator</b>		<b>Size</b>	0.0		
<b>Time Above 217</b>		<b>Reflow Additional Info</b>		<b>Preheat Max Temp</b>		<b>Terminal Base Alloy</b>	NAC		
<b>Preheat Duration</b>		<b>bulk Solder Termination</b>	NAC	<b>Nbr or Reflow Cycles</b>		<b>Terminal Plating</b>	NAC		
<b>Preheat Min Temp</b>		<b>Nbr of Instances</b>	0	<b>Component Temp Spike</b>		<b>Shape</b>	NAC		
<b>Product Disclosure</b>									
<b>Sub-Item/Material/Substance</b>	<b>Level</b>	<b>Name</b>	<b>Substance Category</b>	<b>Substance CAS</b>	<b>Substance Concentration</b>	<b>Quantity</b>	<b>Mass per Unit</b>	<b>UOM</b>	<b>Exemption</b>
Sub-Item	1	Switch contact B Micro SD Nokia				1.0	89.315	mg	
Material	2	Gold Plate				1.0	0.085	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	1.0	0.084745	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	2.55E-4	mg	
Material	2	Copper Alloy				1.0	83.0	mg	
Substance	3	Iron	Supplier	7439-89-6	0.1	1.0	0.083	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	1.0	8.3E-4	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	1.0	0.083	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.0083	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.35	1.0	0.2905	mg	
Substance	3	Zinc	Supplier	7440-66-6	0.2	1.0	0.166	mg	
Substance	3	Tin	Supplier	7440-31-5	11.0	1.0	9.13	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	8.3E-4	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	1.0	0.0083	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.01	1.0	0.0083	mg	
Substance	3	Copper	Supplier	7440-50-8	88.1125	1.0	73.13337	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	4.15E-4	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0050	1.0	0.00415	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.05	1.0	0.0415	mg	

Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.05	1.0	0.0415	mg	
Material	2	Nickel Plate				1.0	6.23	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.00623	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.01246	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	1.0	6.21131	mg	
Sub-Item	1	Shield shell Micro SD Nokia				1.0	230.0	mg	
Material	2	Gold Plate				1.0	0.067	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	1.0	0.066799	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	2.01E-4	mg	
Material	2	Copper Alloy				1.0	205.86	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	1.0	0.20586	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.02	1.0	0.041172	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.020586	mg	
Substance	3	Iron	Supplier	7439-89-6	0.2	1.0	0.41172	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	1.0	0.0020586	mg	
Substance	3	Tin	Supplier	7440-31-5	1.5	1.0	3.0879	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	1.0	0.020586	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.1	1.0	0.20586	mg	
Substance	3	Zinc	Supplier	7440-66-6	21.73	1.0	44.73338	mg	
Substance	3	Copper	Supplier	7440-50-8	76.0475	1.0	156.55138	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	0.0020586	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	0.0010293	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.07	1.0	0.1441	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	1.0	0.41172	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	1.0	0.020586	mg	
Material	2	Nickel Plate				1.0	24.073	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.024073	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.048146	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	1.0	24.00078	mg	
Sub-Item	1	Coil spring Micro SD Nokia				1.0	12.16	mg	
Material	2	Carbon Steel				1.0	12.16	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.001216	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	1.0	0.001216	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	1.0	0.01216	mg	
Substance	3	Iron	Supplier	7439-89-6	97.3835	1.0	11.84183	mg	
Substance	3	Aluminum	Supplier	7429-90-5	0.05	1.0	0.00608	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.6	1.0	0.07296	mg	
Substance	3	Silicon	Supplier	7440-21-3	0.3	1.0	0.03648	mg	
Substance	3	Zinc	Supplier	7440-66-6	0.0050	1.0	6.08E-4	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	1.216E-4	mg	
Substance	3	Tin	Supplier	7440-31-5	0.04	1.0	0.004864	mg	
Substance	3	Sulfur	Supplier	7704-34-9	0.03	1.0	0.003648	mg	
Substance	3	Carbon	Supplier	7440-44-0	1.0	1.0	0.1216	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.15	1.0	0.01824	mg	
Substance	3	Molybdenum	Supplier	7439-98-7	0.01	1.0	0.001216	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.03	1.0	0.003648	mg	
Substance	3	Vanadium	Supplier	7440-62-2	0.02	1.0	0.002432	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.15	1.0	0.01824	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.01216	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	1.0	0.001216	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	6.08E-5	mg	
Sub-Item	1	Hook spring Micro SD Nokia				1.0	8.0	mg	
Material	2	Stainless Steel				1.0	8.0	mg	

Substance	3	Chromium	Supplier	7440-47-3	18.0	1.0	1.44	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.5	1.0	0.04	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.045	1.0	0.0036	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	8.0E-4	mg	
Substance	3	Carbon	Supplier	7440-44-0	0.15	1.0	0.012	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.01	1.0	8.0E-4	mg	
Substance	3	Silicon	Supplier	7440-21-3	1.5	1.0	0.12	mg	
Substance	3	Manganese	Supplier	7439-96-5	2.0	1.0	0.16	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.03	1.0	0.0024	mg	
Substance	3	Sulfur	Supplier	7704-34-9	0.03	1.0	0.0024	mg	
Substance	3	Iron	Supplier	7439-89-6	68.6147	1.0	5.48918	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	0.007992	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0099	1.0	7.92E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	9.0	1.0	0.72	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	4.0E-5	mg	
Sub-Item	1	Micro SD Nokia slider				1.0	20.0	mg	
Material	2	LCP-GF30				1.0	20.0	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	1.0	1.0	0.2	mg	
Substance	3	Phenol	Supplier	108-95-2	0.0040	1.0	8.0E-4	mg	
Substance	3	1,4-Benzenedicarboxylic acid, polymer with [1,1-biphenyl]-4,4-diol, 4-hydroxybenzoic acid, 6-hydroxy-2-naphthalenecarboxylic acid and N-(4-hydroxyphenyl)acetamide	Supplier	147310-94-9	67.996	1.0	13.5992	mg	
Substance	3	Carbon black	Supplier	1333-86-4	1.0	1.0	0.2	mg	
Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	30.0	1.0	6.0	mg	
Sub-Item	1	Cam rod Micro SD Nokia				1.0	4.267	mg	
Material	2	Stainless Steel				1.0	4.267	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0099	1.0	4.2243E-4	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	4.267E-5	mg	
Substance	3	Manganese	Supplier	7439-96-5	2.0	1.0	0.08534	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.05	1.0	0.0021335	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.35	1.0	0.0149345	mg	
Substance	3	Chromium	Supplier	7440-47-3	20.0	1.0	0.8534	mg	
Substance	3	Sulfur	Supplier	7704-34-9	0.03	1.0	0.0012801	mg	
Substance	3	Silicon	Supplier	7440-21-3	1.0	1.0	0.04267	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	1.0	4.267E-4	mg	
Substance	3	Carbon	Supplier	7440-44-0	0.08	1.0	0.0034136	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	4.267E-4	mg	
Substance	3	Iron	Supplier	7439-89-6	64.3587	1.0	2.74619	mg	
Substance	3	Nickel	Nickel	7440-02-0	12.0	1.0	0.51204	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.0999	1.0	0.00426273	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	2.1335E-5	mg	
Sub-Item	1	Switch contact A Micro SD Nokia				1.0	45.5566	mg	
Material	2	Gold Plate				1.0	0.062	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	1.0	0.061814	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	1.86E-4	mg	
Material	2	Brass				1.0	42.0	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	1.0	4.2E-4	mg	
Substance	3	Zinc	Supplier	7440-66-6	28.0225	1.0	11.76945	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.05	1.0	0.021	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.0042	mg	
Substance	3	Iron	Supplier	7439-89-6	0.05	1.0	0.021	mg	

Substance	3	Cobalt	Supplier	7440-48-4	0.1	1.0	0.042	mg	
Substance	3	Copper	Supplier	7440-50-8	71.5	1.0	30.03	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	4.2E-4	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	1.0	0.0042	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	2.1E-4	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	1.0	0.084	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.0050	1.0	0.0021	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.05	1.0	0.021	mg	
Material	2	Tin Plate				1.0	0.0236	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	4.72E-5	mg	
Substance	3	Tin	Supplier	7440-31-5	99.73	1.0	0.02353628	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.07	1.0	1.652E-5	mg	
Material	2	Nickel Plate				1.0	3.471	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.003471	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.006942	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	1.0	3.46059	mg	
Sub-Item	1	Over molding Micro SD Nokia				1.0	531.073	mg	
Material	2	Gold Plate				1.0	0.179	mg	
Substance	3	Gold	Supplier	7440-57-5	99.7	1.0	0.17846	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.3	1.0	5.37E-4	mg	
Material	2	LCP-(MD+GF)30				1.0	225.0	mg	
Substance	3	Carbon black	Supplier	1333-86-4	1.0	1.0	2.25	mg	
Substance	3	Phenol	Supplier	108-95-2	0.0040	1.0	0.0090	mg	
Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	10.0	1.0	22.5	mg	
Substance	3	1,4-Benzenedicarboxylic acid, polymer with [1,1-biphenyl]-4,4-diol, 4-hydroxybenzoic acid and 6-hydroxy-2-naphthalenecarboxylic acid, acetate, potassium salt	Supplier	132699-78-6	66.996	1.0	150.741	mg	
Substance	3	Mica-group minerals	Supplier	12001-26-2	22.0	1.0	49.5	mg	
Material	2	Copper Alloy				1.0	295.0	mg	
Substance	3	Cobalt	Supplier	7440-48-4	0.1	1.0	0.295	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.02	1.0	0.059	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.0295	mg	
Substance	3	Iron	Supplier	7439-89-6	0.2	1.0	0.59	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.0010	1.0	0.00295	mg	
Substance	3	Tin	Supplier	7440-31-5	1.5	1.0	4.425	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.01	1.0	0.0295	mg	
Substance	3	Phosphorus	Supplier	7723-14-0	0.1	1.0	0.295	mg	
Substance	3	Zinc	Supplier	7440-66-6	21.73	1.0	64.1035	mg	
Substance	3	Copper	Supplier	7440-50-8	76.0475	1.0	224.34013	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	0.00295	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	0.001475	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.07	1.0	0.2065	mg	
Substance	3	Nickel	Nickel	7440-02-0	0.2	1.0	0.59	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	1.0	0.0295	mg	
Material	2	Nickel Plate				1.0	10.894	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.010894	mg	

Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.021788	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	1.0	10.86132	mg	